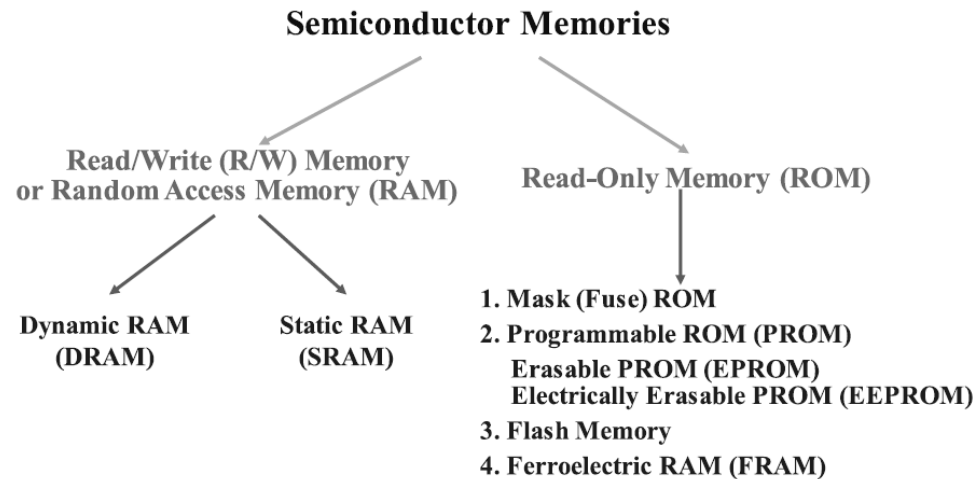


Semiconductor Memories

Semiconductor Memory Types

Semiconductor Memory Types



Semiconductor Memory Types(Cont.)

□ Design Issues

- **Area Efficiency of Memory Array:** # of stored data bits per unit area
- **Memory Access Time:** the time required to store and/or retrieve a particular data bit.
- **Static and Dynamic Power Consumption**

□ RAM: the stored data is volatile

• *DRAM*

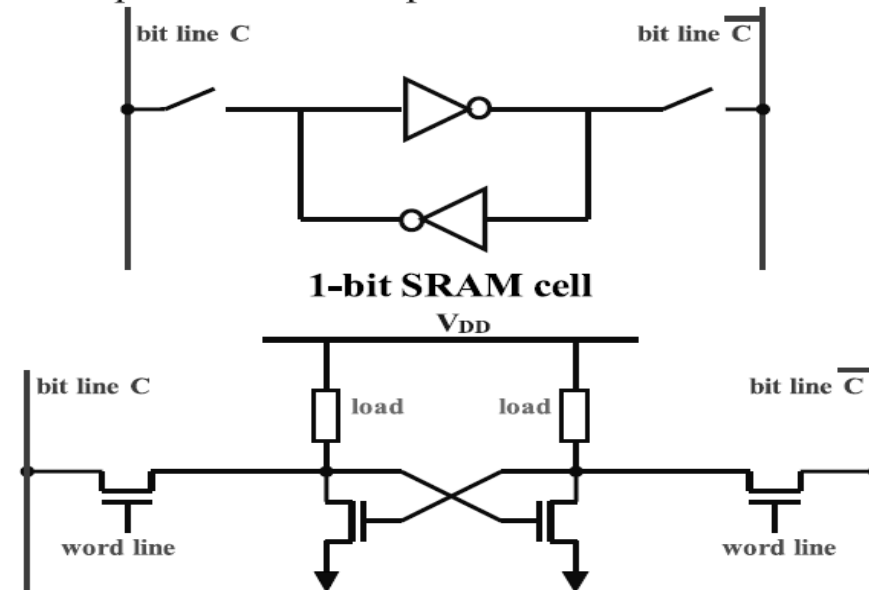
- » A capacitor to store data, and a transistor to access the capacitor
- » **Need refresh operation**
- » **Low cost**, and **high density** \Rightarrow it is used for main memory

• *SRAM*

- » Consists of a latch
- » **Don't need the refresh operation**
- » **High speed** and **low power consumption** \Rightarrow it is mainly used for cache memory and memory in hand-held devices

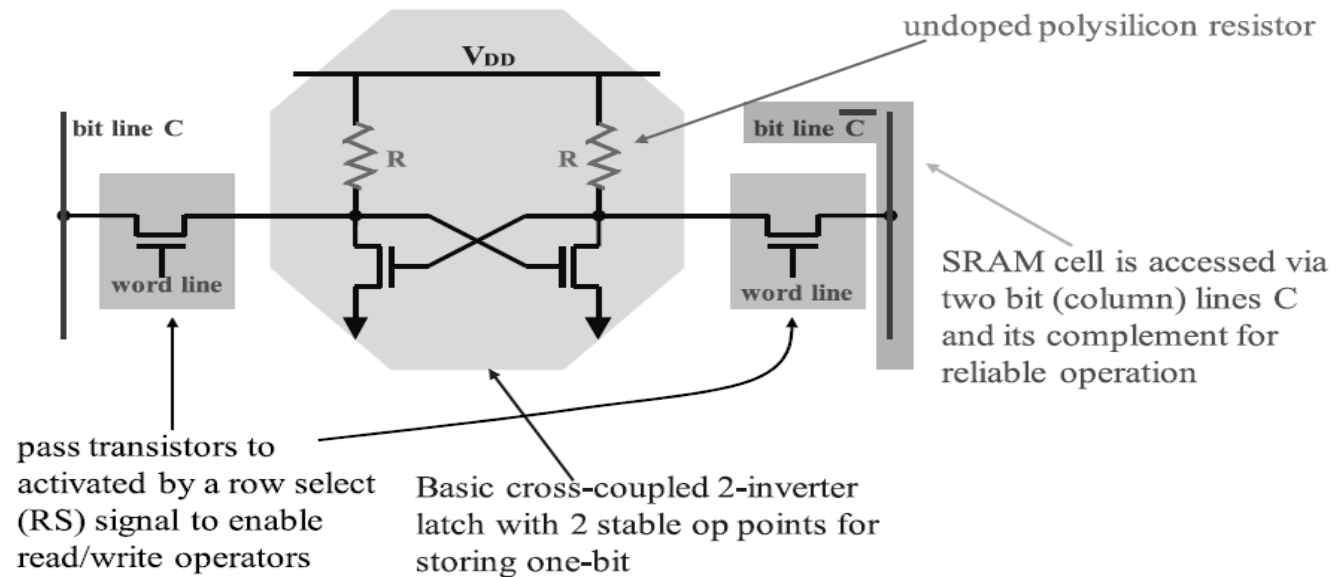
Static Random-Access Memory (SRAM)

- **SRAM:** The stored data can be retained indefinitely, without any need for a periodic refresh operation.

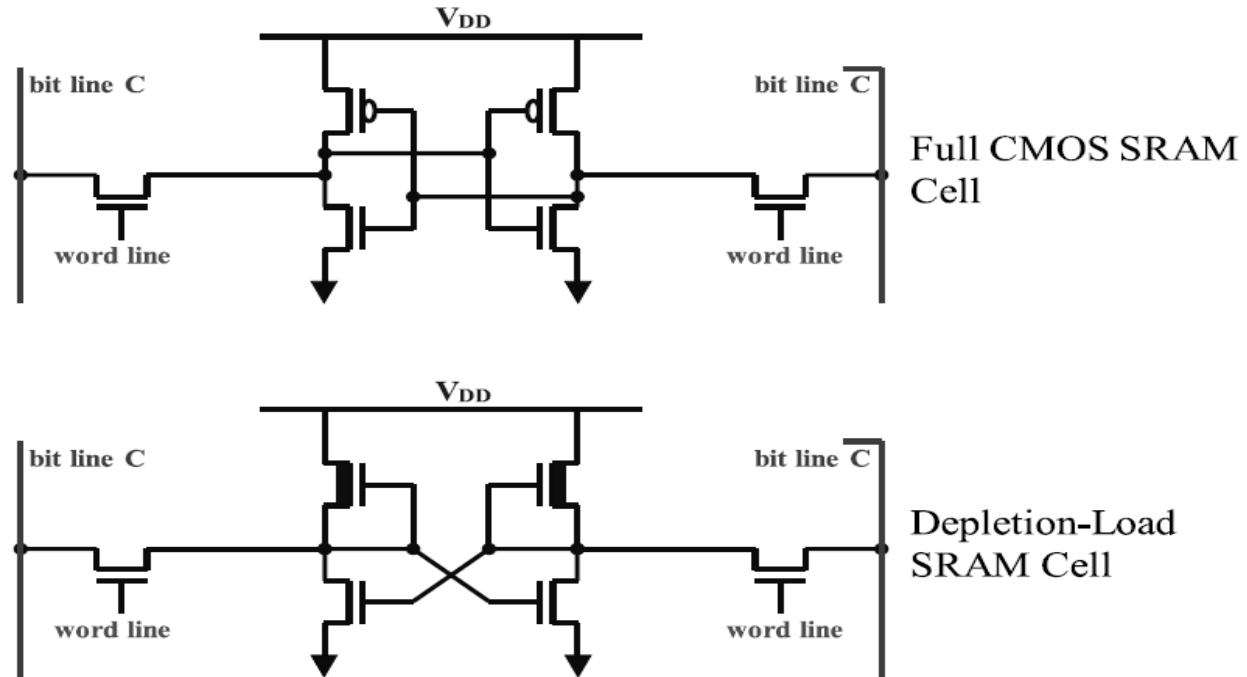


- **Complementary Column** arrangement is to achieve a more reliable SRAM operation

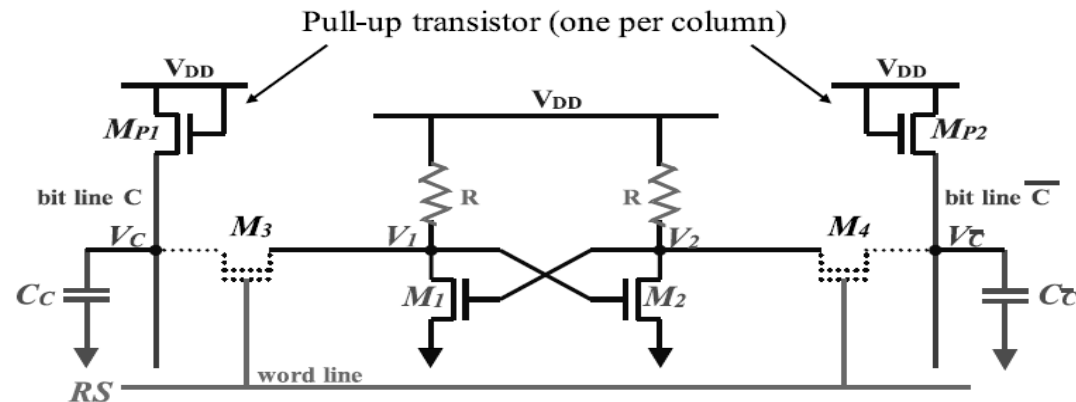
Resistive-Load SRAM Cell



Full CMOS Depletion-Load SRAM Cell



SRAM Operation Principles

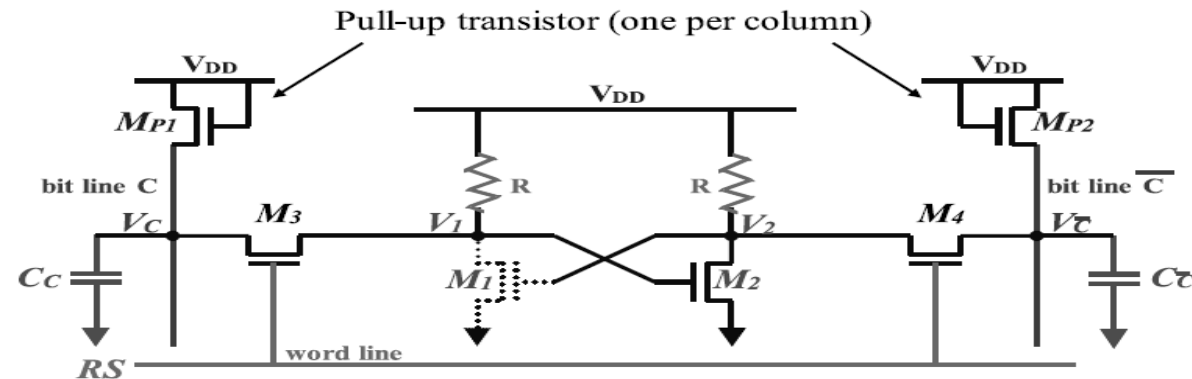


- **$RS=0$:** The word line is not selected. M_3 and M_4 are OFF
- One data-bit is held: The latch preserves one of its two stable states.
- **If $RS=0$ for all rows:** C_C and $C_{\overline{C}}$ are charged up to near V_{DD} by pulling up of M_{P1} and M_{P2} (both in saturation)

$$V_{\bar{C}} = V_C = V_{DD} - \left(V_{T0} + \gamma \sqrt{|2\phi_F| + V_C} - \sqrt{|2\phi_F|} \right)$$

- Ex: $V_C = V_{\overline{C}} = 3.5\text{V}$ for $V_{DD} = 5\text{V}$, $V_{T0} = 1\text{V}$, $|2\phi_F| = 0.6\text{V}$

SRAM Operation Principles (Cont.)



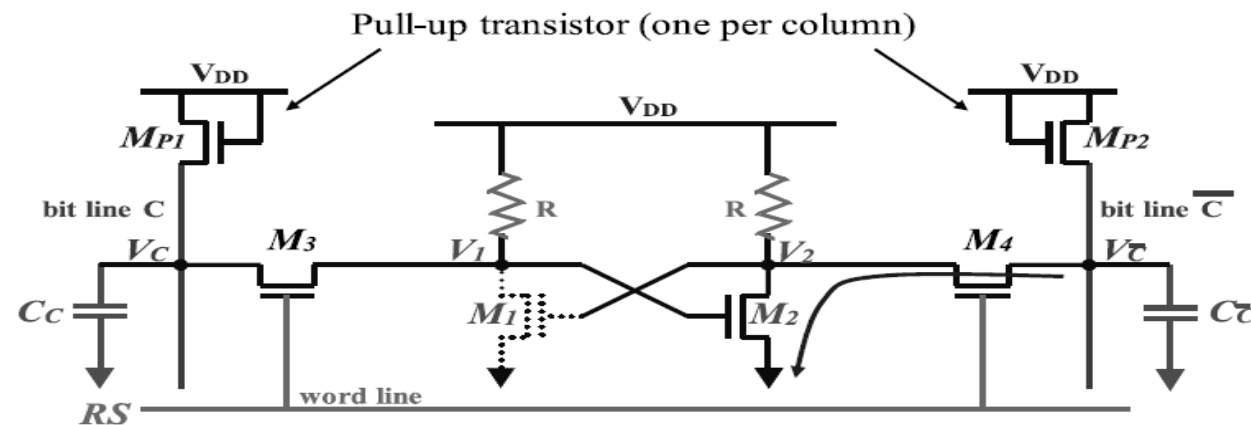
- $RS=1$: The word line is now selected. M_3 and M_4 are ON

Four Operations

1. Write "1" Operation ($V_1=V_{OL}$, $V_2=V_{OH}$ at $t=0$):

$V_{\bar{C}} \Rightarrow V_{OL}$ by the *data-write circuitry*. Therefore, $V_2 \Rightarrow V_{OL}$, then M_1 turns **off** $V_1 \Rightarrow V_{OH}$ and M_2 turns on pulling down $V_2 \Rightarrow V_{OL}$.

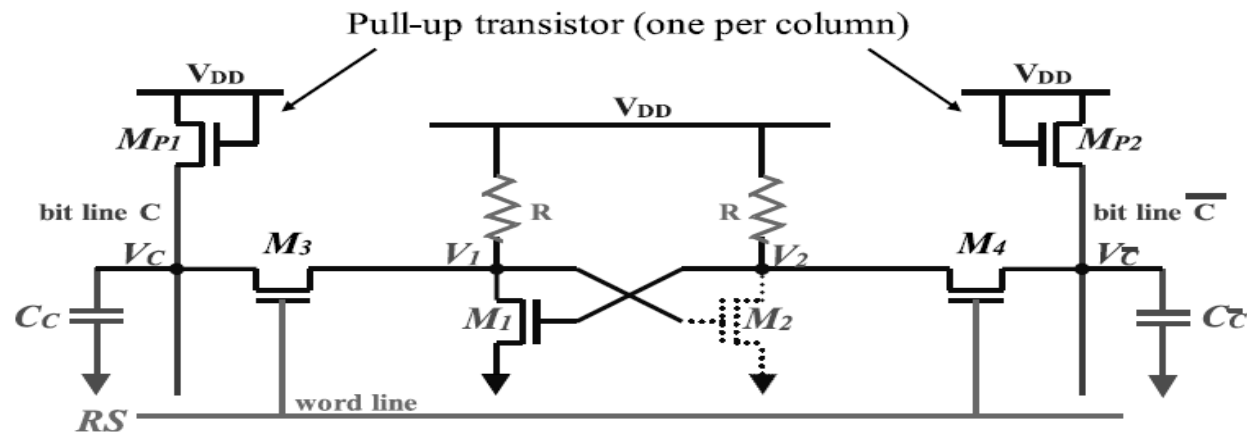
SRAM Operation Principles (Cont.)



2. Read "1" Operation ($V_1=V_{OH}$, $V_2=V_{OL}$ at $t=0$):

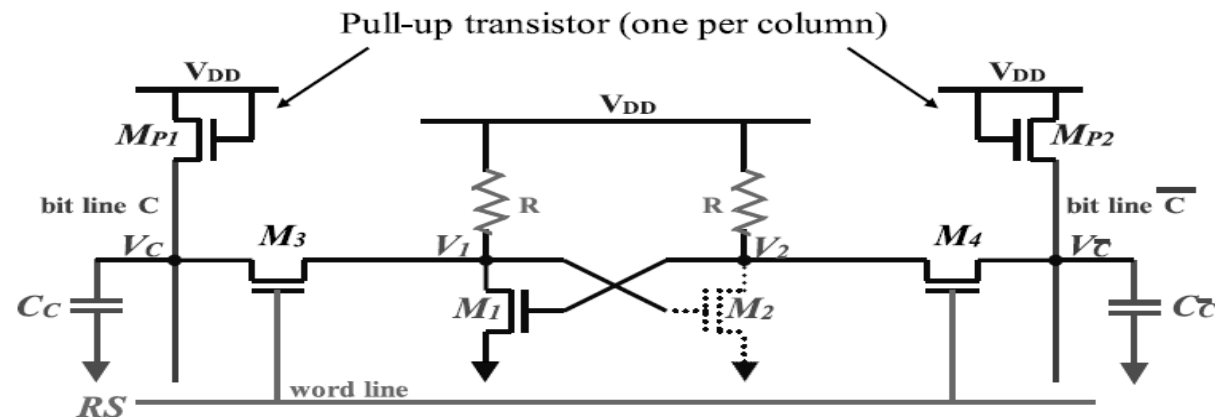
V_C retains pre-charge level, while $V_{\bar{C}} \Rightarrow V_{OL}$ by M_2 ON. *Data-read circuitry* detects small voltage difference $V_C - V_{\bar{C}} > 0$, and amplifies it as a "1" data output.

SRAM Operation Principles (Cont.)



3. Write "0" Operation ($V_1=V_{OH}$, $V_2=V_{OL}$ at $t=0$):
 $V_C \Rightarrow V_{OL}$ by the *data-write circuitry*.
Since $V_1 \Rightarrow V_{OL}$, M_2 turns off, therefore $V_2 \Rightarrow V_{OH}$.

SRAM Operation Principles (Cont.)

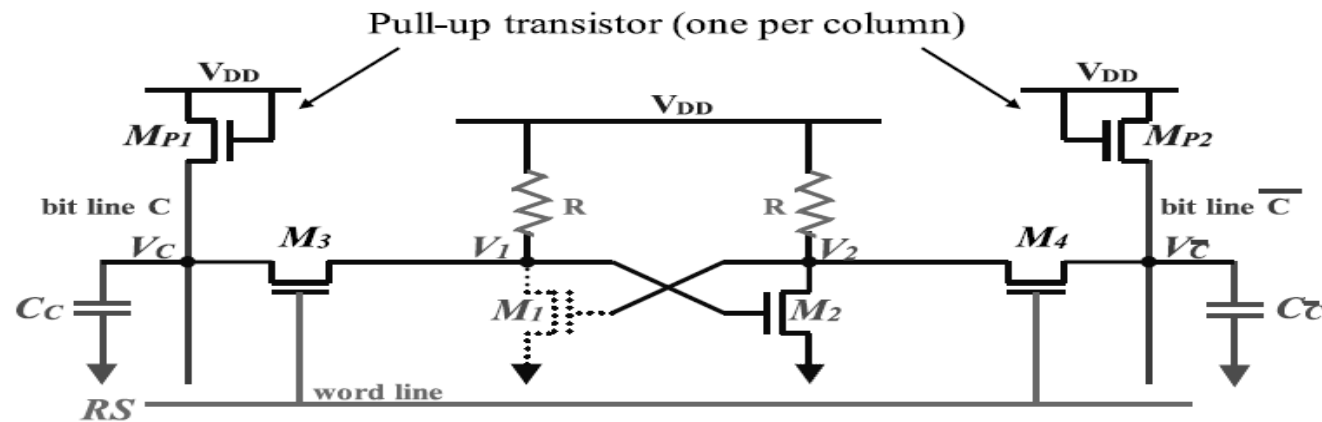


4. Read "0" Operation ($V_1=V_{OL}$, $V_2=V_{OH}$ at $t=0$):

$V_{\bar{C}}$ retains pre-charge level, while $V_C \Rightarrow V_{OL}$ by M_1 ON.

Data-read circuitry detects small voltage difference $V_C - V_{\bar{C}} < 0$, and amplifies it as a "0" data output.

Static or “Standby” Power Consumption

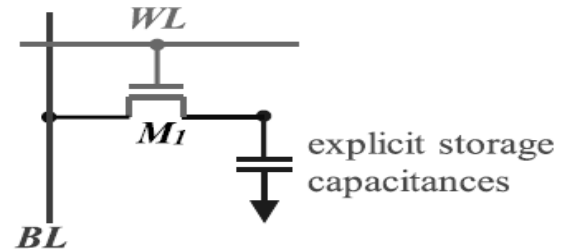


- **Assume:** 1 bit is stored in the cell $\Rightarrow M_1$ OFF, M_2 ON $\Rightarrow V_1 = V_{OH}$, $V_2 = V_{OL}$. I.E. One load resistor is always conducting non-zero current.

$$P_{\text{standby}} = (V_{DD} - V_{OL})^2 / R$$

with $R = 100\text{M}\Omega$ (undoped poly), $P_{\text{standby}} \approx 0.25 \mu\text{W}$ per cell for $V_{DD} = 5\text{V}$

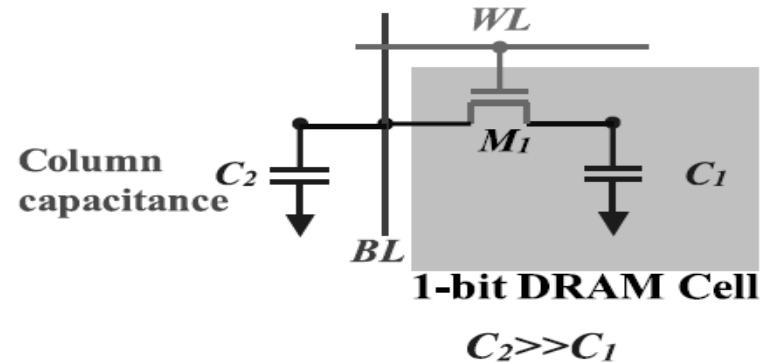
1-T DRAM Cell



One-Transistor DRAM Cell

- **Industry standard** for high density dram arrays
- **Smallest** component count and silicon area per bit
- Separate or “**explicit**” capacitor (dual poly) per cell

Operation of 1-T DRAM Cell



- **Write "1" OP:** $BL = 1, WL = 1$ (M_1 ON) $\Rightarrow C_1$ charges to "1"
- **Write "0" OP:** $BL = 0, WL = 1$ (M_1 ON) $\Rightarrow C_1$ discharges to "0"
- **Read OP:** destroys stored charge on $C_1 \Rightarrow$ destructive refresh is needed after every data read operation

Thank You